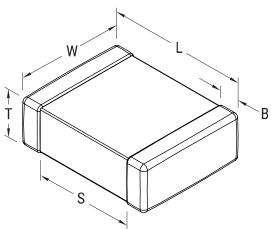


C0805C334M5REC7210

ESD SMD Comm X7R, Ceramic, 0.33 uF, 20%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0805, 0.7 mm





Click here for the 3D model.	Series	ESD SMD Comm X7R
	Style	SMD Chip
	Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
	Features	Temperature Stable, Class II
	RoHS	Yes
	Termination	Tin
	Marking	No
	AEC-Q200	No
	Typical Component Weight	13 mg
	Shelf Life	78 Weeks
	MSL	1

General Information

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications	
Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.5152 GOhms

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